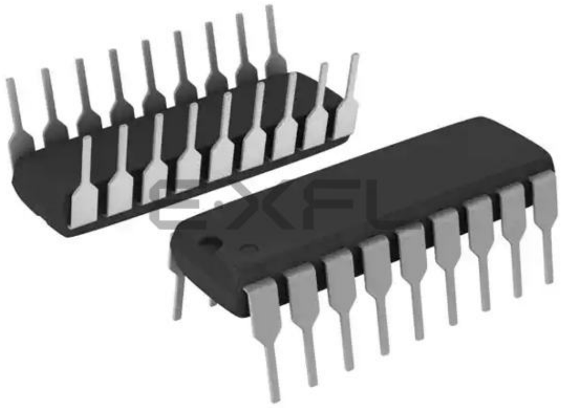

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	80 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc621-04e-p

TABLE 1-1: PIC16C62X FAMILY OF DEVICES

		PIC16C620(3)	PIC16C620A(1)(4)	PIC16CR620A(2)	PIC16C621(3)	PIC16C621A(1)(4)	PIC16C622(3)	PIC16C622A(1)(4)
Clock	Maximum Frequency of Operation (MHz)	20	40	20	20	40	20	40
Memory	EPROM Program Memory (x14 words)	512	512	512	1K	1K	2K	2K
	Data Memory (bytes)	80	96	96	80	96	128	128
Peripherals	Timer Module(s)	TMR0	TMR0	TMRO	TMR0	TMR0	TMR0	TMR0
	Comparators(s)	2	2	2	2	2	2	2
	Internal Reference Voltage	Yes	Yes	Yes	Yes	Yes	Yes	Yes
Features	Interrupt Sources	4	4	4	4	4	4	4
	I/O Pins	13	13	13	13	13	13	13
	Voltage Range (Volts)	2.5-6.0	2.7-5.5	2.5-5.5	2.5-6.0	2.7-5.5	2.5-6.0	2.7-5.5
	Brown-out Reset	Yes	Yes	Yes	Yes	Yes	Yes	Yes
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP

All PICmicro® Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C62X Family devices use serial programming with clock pin RB6 and data pin RB7.

Note 1: If you change from this device to another device, please verify oscillator characteristics in your application.

2: For ROM parts, operation from 2.0V - 2.5V will require the PIC16LCR62XA parts.

3: For OTP parts, operation from 2.5V - 3.0V will require the PIC16LC62X part.

4: For OTP parts, operation from 2.7V - 3.0V will require the PIC16LC62XA part.

2.0 PIC16C62X DEVICE VARIETIES

A variety of frequency ranges and packaging options are available. Depending on application and production requirements, the proper device option can be selected using the information in the PIC16C62X Product Identification System section at the end of this data sheet. When placing orders, please use this page of the data sheet to specify the correct part number.

2.1 UV Erasable Devices

The UV erasable version, offered in CERDIP package, is optimal for prototype development and pilot programs. This version can be erased and reprogrammed to any of the Oscillator modes.

Microchip's PICSTART® and PRO MATE® programmers both support programming of the PIC16C62X.

Note:	Microchip does not recommend code protecting windowed devices.

2.2 One-Time-Programmable (OTP) Devices

The availability of OTP devices is especially useful for customers who need the flexibility for frequent code updates and small volume applications. In addition to the program memory, the configuration bits must also be programmed.

2.3 Quick-Turnaround-Production (QTP) Devices

Microchip offers a QTP programming service for factory production orders. This service is made available for users who chose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices, but with all EPROM locations and configuration options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. Please contact your Microchip Technology sales office for more details.

2.4 Serialized Quick-Turnaround-Production℠ (SQTP℠) Devices

Microchip offers a unique programming service where a few user-defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random or sequential.

Serial programming allows each device to have a unique number, which can serve as an entry-code, password or ID number.

4.2 Data Memory Organization

The data memory (Figure 4-4, Figure 4-5, Figure 4-6 and Figure 4-7) is partitioned into two banks, which contain the General Purpose Registers and the Special Function Registers. Bank 0 is selected when the RP0 bit is cleared. Bank 1 is selected when the RP0 bit (STATUS <5>) is set. The Special Function Registers are located in the first 32 locations of each bank. Register locations 20-7Fh (Bank0) on the PIC16C620A/CR620A/621A and 20-7Fh (Bank0) and A0-BFh (Bank1) on the PIC16C622 and PIC16C622A are General Purpose Registers implemented as static RAM. Some Special Purpose Registers are mapped in Bank 1.

Addresses F0h-FFh of bank1 are implemented as common ram and mapped back to addresses 70h-7Fh in bank0 on the PIC16C620A/621A/622A/CR620A.

4.2.1 GENERAL PURPOSE REGISTER FILE

The register file is organized as 80 x 8 in the PIC16C620/621, 96 x 8 in the PIC16C620A/621A/CR620A and 128 x 8 in the PIC16C622(A). Each is accessed either directly or indirectly through the File Select Register FSR (Section 4.4).

5.2 PORTB and TRISB Registers

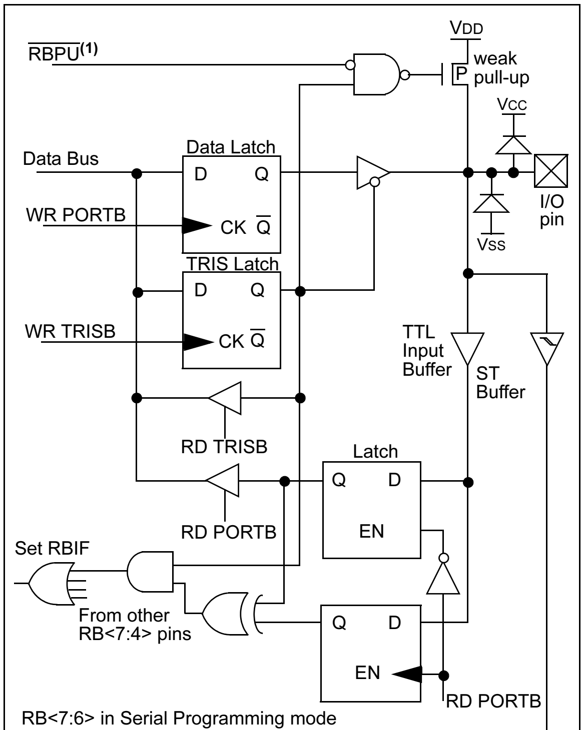
PORTB is an 8-bit wide, bi-directional port. The corresponding data direction register is TRISB. A '1' in the TRISB register puts the corresponding output driver in a High Impedance mode. A '0' in the TRISB register puts the contents of the output latch on the selected pin(s).

Reading PORTB register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. So a write to a port implies that the port pins are first read, then this value is modified and written to the port data latch.

Each of the PORTB pins has a weak internal pull-up (≈200 μA typical). A single control bit can turn on all the pull-ups. This is done by clearing the $\overline{\text{RBPU}}$ (OPTION<7>) bit. The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on Power-on Reset.

Four of PORTB's pins, RB<7:4>, have an interrupt on change feature. Only pins configured as inputs can cause this interrupt to occur (e.g., any RB<7:4> pin configured as an output is excluded from the interrupt on change comparison). The input pins (of RB<7:4>) are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB<7:4> are OR'ed together to generate the RBIF interrupt (flag latched in INTCON<0>).

FIGURE 5-5: BLOCK DIAGRAM OF RB<7:4> PINS



Note 1: TRISB = 1 enables weak pull-up if $\overline{\text{RBPU}}$ = '0' (OPTION<7>).

This interrupt can wake the device from SLEEP. The user, in the interrupt service routine, can clear the interrupt in the following manner:

a) Any read or write of PORTB. This will end the mismatch condition.
b) Clear flag bit RBIF.

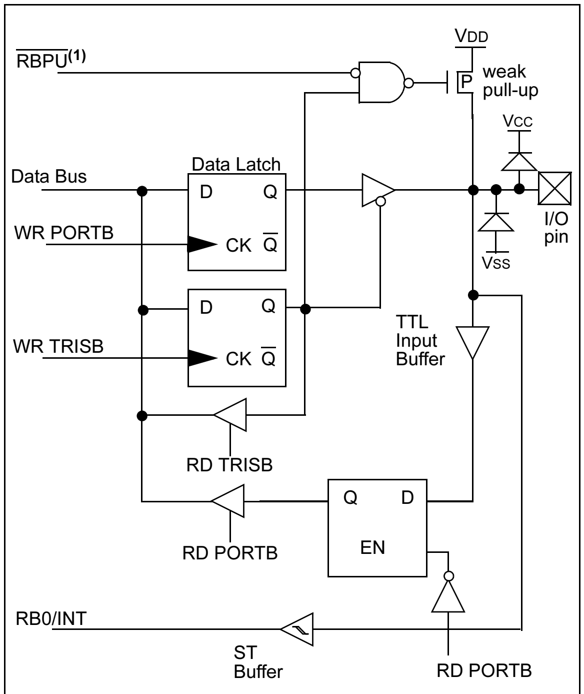
A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition and allow flag bit RBIF to be cleared.

This interrupt on mismatch feature, together with software configurable pull-ups on these four pins allow easy interface to a key pad and make it possible for wake-up on key-depression. (See AN552, "Implementing Wake-Up on Key Strokes.)

Note:	If a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the RBIF interrupt flag may not get set.

The interrupt-on-change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt on change feature. Polling of PORTB is not recommended while using the interrupt-on-change feature.

FIGURE 5-6: BLOCK DIAGRAM OF RB<3:0> PINS



Note 1: TRISB = 1 enables weak pull-up if $\overline{\text{RBPU}}$ = '0' (OPTION<7>).

9.0 SPECIAL FEATURES OF THE CPU

Special circuits to deal with the needs of real-time applications are what sets a microcontroller apart from other processors. The PIC16C62X family has a host of such features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving operating modes and offer code protection.

These are:

1. OSC selection
2. RESET
   Power-on Reset (POR)
   Power-up Timer (PWRT)
   Oscillator Start-up Timer (OST)
   Brown-out Reset (BOR)
3. Interrupts
4. Watchdog Timer (WDT)
5. SLEEP
6. Code protection
7. ID Locations
8. In-Circuit Serial Programming™

The PIC16C62X devices have a Watchdog Timer which is controlled by configuration bits. It runs off its own RC oscillator for added reliability. There are two timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), intended to keep the chip in RESET until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay of 72 ms (nominal) on power-up only, designed to keep the part in RESET while the power supply stabilizes. There is also circuitry to RESET the device if a brown-out occurs, which provides at least a 72 ms RESET. With these three functions on-chip, most applications need no external RESET circuitry.

The SLEEP mode is designed to offer a very low current Power-down mode. The user can wake-up from SLEEP through external RESET, Watchdog Timer wake-up or through an interrupt. Several oscillator options are also made available to allow the part to fit the application. The RC oscillator option saves system cost, while the LP crystal option saves power. A set of configuration bits are used to select various options.

9.1 Configuration Bits

The configuration bits can be programmed (read as '0') or left unprogrammed (read as '1') to select various device configurations. These bits are mapped in program memory location 2007h.

The user will note that address 2007h is beyond the user program memory space. In fact, it belongs to the special test/configuration memory space (2000h – 3FFFh), which can be accessed only during programming.

REGISTER 9-1: CONFIGURATION WORD (ADDRESS 2007h)

CP1	CP0 (2)	CP1	$\overline{\text{CP0}}$ (2)	$\overline{\text{CP1}}$	CP0 (2)		BODEN	CP1	CP0 (2)	$\overline{\text{PWRTE}}$	WDTE	F0SC1	F0SC0

bit 13 ... bit 0

bit 13-8, 5-4: **CP<1:0>:** Code protection bit pairs (2)

Code protection for 2K program memory
`11` = Program memory code protection off
`10` = 0400h-07FFh code protected
`01` = 0200h-07FFh code protected
`00` = 0000h-07FFh code protected

Code protection for 1K program memory
`11` = Program memory code protection off
`10` = Program memory code protection off
`01` = 0200h-03FFh code protected
`00` = 0000h-03FFh code protected

Code protection for 0.5K program memory
`11` = Program memory code protection off
`10` = Program memory code protection off
`01` = Program memory code protection off
`00` = 0000h-01FFh code protected

bit 7 **Unimplemented**: Read as ‘0’

bit 6 **BODEN**: Brown-out Reset Enable bit (1)
`1` = BOR enabled
`0` = BOR disabled

bit 3 **$\overline{\text{PWRTE}}$**: Power-up Timer Enable bit (1, 3)
`1` = PWRT disabled
`0` = PWRT enabled

bit 2 **WDTE**: Watchdog Timer Enable bit
`1` = WDT enabled
`0` = WDT disabled

bit 1-0 **FOSC1:FOSC0**: Oscillator Selection bits
`11` = RC oscillator
`10` = HS oscillator
`01` = XT oscillator
`00` = LP oscillator

Note 1: Enabling Brown-out Reset automatically enables Power-up Timer (PWRT) regardless of the value of bit $\overline{\text{PWRTE}}$. Ensure the Power-up Timer is enabled anytime Brown-out Detect Reset is enabled.

2: All of the CP<1:0> pairs have to be given the same value to enable the code protection scheme listed.

3: Unprogrammed parts default the Power-up Timer disabled.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	1 = bit is set	0 = bit is cleared	x = bit is unknown

9.5 Interrupts

The PIC16C62X has 4 sources of interrupt:

- External interrupt RB0/INT
- TMR0 overflow interrupt
- PORTB change interrupts (pins RB<7:4>)
- Comparator interrupt

The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

A global interrupt enable bit, GIE (INTCON<7>) enables (if set) all un-masked interrupts or disables (if cleared) all interrupts. Individual interrupts can be disabled through their corresponding enable bits in INTCON register. GIE is cleared on RESET.

The "return from interrupt" instruction, `RETFIE`, exits interrupt routine, as well as sets the GIE bit, which re-enable RB0/INT interrupts.

The INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flag is contained in the special register PIR1. The corresponding interrupt enable bit is contained in special registers PIE1.

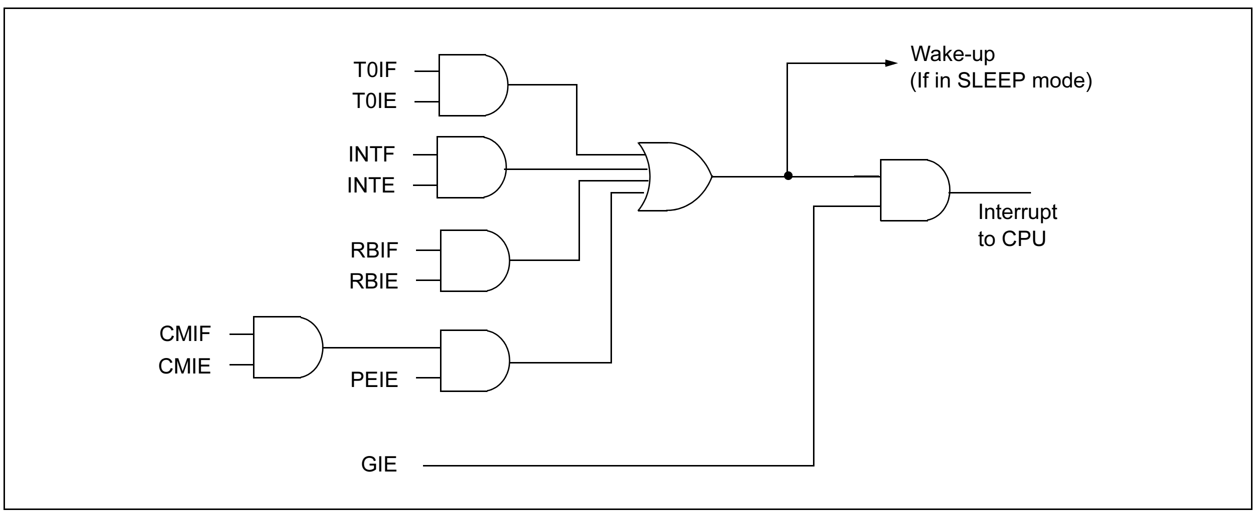
When an interrupt is responded to, the GIE is cleared to disable any further interrupt, the return address is pushed into the stack and the PC is loaded with 0004h.

Once in the interrupt service routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid RB0/INT recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs (Figure 9-16). The latency is the same for one or two cycle instructions. Once in the interrupt service routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid multiple interrupt requests.

> **Note 1:** Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.
>
> **2:** When an instruction that clears the GIE bit is executed, any interrupts that were pending for execution in the next cycle are ignored. The CPU will execute a `NOP` in the cycle immediately following the instruction which clears the GIE bit. The interrupts which were ignored are still pending to be serviced when the GIE bit is set again.

FIGURE 9-15: INTERRUPT LOGIC



BTFSS	Bit Test f, Skip if Set			
Syntax:	[*label*] BTFSS f,b			
Operands:	$0 \leq f \leq 127$ $0 \leq b < 7$			
Operation:	skip if (f<b>) = 1			
Status Affected:	None			
Encoding:	`01`	`11bb`	`bfff`	`ffff`
Description:	If bit 'b' in register 'f' is '1', then the next instruction is skipped. If bit 'b' is '1', then the next instruction fetched during the current instruction execution, is discarded and a `NOP` is executed instead, making this a two-cycle instruction.			
Words:	1			
Cycles:	1(2)			
Example	`HERE BTFSS` FLAG,1 `FALSE GOTO` PROCESS_CODE `TRUE` • • • Before Instruction PC = address `HERE` After Instruction if FLAG<1> = 0, PC = address `FALSE` if FLAG<1> = 1, PC = address `TRUE`			

CALL	Call Subroutine			
Syntax:	[*label*] CALL k			
Operands:	$0 \leq k \leq 2047$			
Operation:	(PC)+ 1→ TOS, k → PC<10:0>, (PCLATH<4:3>) → PC<12:11>			
Status Affected:	None			
Encoding:	`10`	`0kkk`	`kkkk`	`kkkk`
Description:	Call Subroutine. First, return address (PC+1) is pushed onto the stack. The eleven bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. `CALL` is a two-cycle instruction.			
Words:	1			
Cycles:	2			
Example	`HERE CALL` THERE Before Instruction PC = Address `HERE` After Instruction PC = Address `THERE` TOS = Address `HERE+1`			

CLRF	Clear f			
Syntax:	[*label*] CLRF f			
Operands:	$0 \leq f \leq 127$			
Operation:	00h → (f) 1 → Z			
Status Affected:	Z			
Encoding:	`00`	`0001`	`1fff`	`ffff`
Description:	The contents of register 'f' are cleared and the Z bit is set.			
Words:	1			
Cycles:	1			
Example	`CLRF FLAG_REG` Before Instruction FLAG_REG = 0x5A After Instruction FLAG_REG = 0x00 Z = 1			

11.14 PICDEM 1 PICmicro Demonstration Board

The PICDEM 1 demonstration board demonstrates the capabilities of the PIC16C5X (PIC16C54 to PIC16C58A), PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The sample microcontrollers provided with the PICDEM 1 demonstration board can be programmed with a PRO MATE II device programmer, or a PICSTART Plus development programmer. The PICDEM 1 demonstration board can be connected to the MPLAB ICE in-circuit emulator for testing. A prototype area extends the circuitry for additional application components. Features include an RS-232 interface, a potentiometer for simulated analog input, push button switches and eight LEDs.

11.15 PICDEM.net Internet/Ethernet Demonstration Board

The PICDEM.net demonstration board is an Internet/ Ethernet demonstration board using the PIC18F452 microcontroller and TCP/IP firmware. The board supports any 40-pin DIP device that conforms to the standard pinout used by the PIC16F877 or PIC18C452. This kit features a user friendly TCP/IP stack, web server with HTML, a 24L256 Serial EEPROM for Xmodem download to web pages into Serial EEPROM, ICSP/MPLAB ICD 2 interface connector, an Ethernet interface, RS-232 interface, and a 16 x 2 LCD display. Also included is the book and CD-ROM *"TCP/IP Lean, Web Servers for Embedded Systems,"* by Jeremy Bentham

11.16 PICDEM 2 Plus Demonstration Board

The PICDEM 2 Plus demonstration board supports many 18-, 28-, and 40-pin microcontrollers, including PIC16F87X and PIC18FXX2 devices. All the necessary hardware and software is included to run the demonstration programs. The sample microcontrollers provided with the PICDEM 2 demonstration board can be programmed with a PRO MATE II device programmer, PICSTART Plus development programmer, or MPLAB ICD 2 with a Universal Programmer Adapter. The MPLAB ICD 2 and MPLAB ICE in-circuit emulators may also be used with the PICDEM 2 demonstration board to test firmware. A prototype area extends the circuitry for additional application components. Some of the features include an RS-232 interface, a 2 x 16 LCD display, a piezo speaker, an on-board temperature sensor, four LEDs, and sample PIC18F452 and PIC16F877 FLASH microcontrollers.

11.17 PICDEM 3 PIC16C92X Demonstration Board

The PICDEM 3 demonstration board supports the PIC16C923 and PIC16C924 in the PLCC package. All the necessary hardware and software is included to run the demonstration programs.

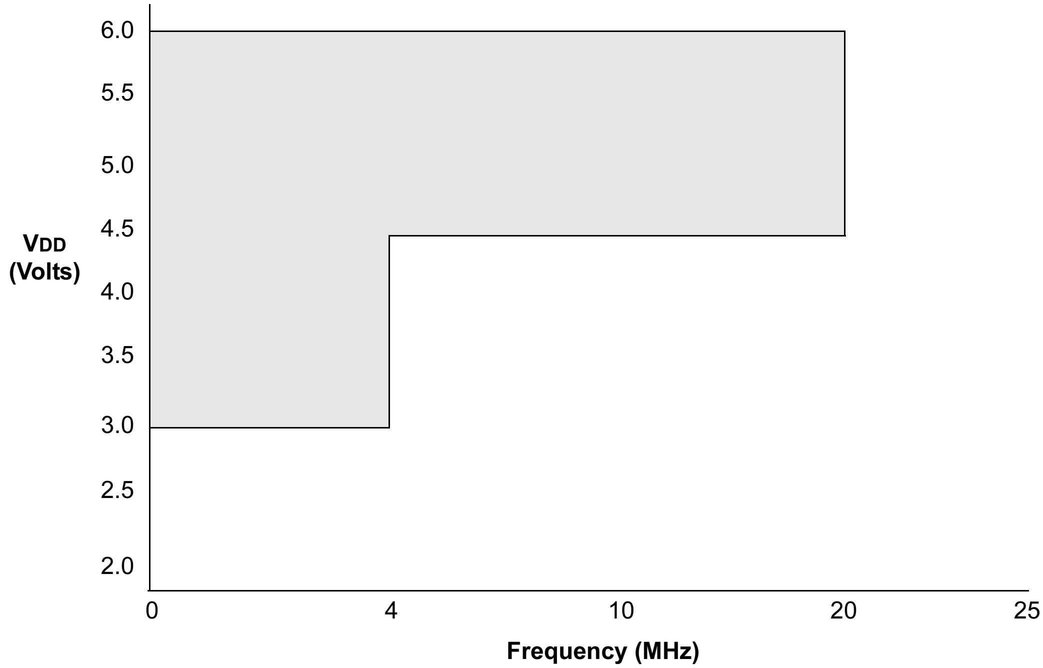
11.18 PICDEM 4 8/14/18-Pin Demonstration Board

The PICDEM 4 can be used to demonstrate the capabilities of the 8-, 14-, and 18-pin PIC16XXXX and PIC18XXXX MCUs, including the PIC16F818/819, PIC16F87/88, PIC16F62XA and the PIC18F1320 family of microcontrollers. PICDEM 4 is intended to showcase the many features of these low pin count parts, including LIN and Motor Control using ECCP. Special provisions are made for low power operation with the supercapacitor circuit, and jumpers allow on-board hardware to be disabled to eliminate current draw in this mode. Included on the demo board are provisions for Crystal, RC or Canned Oscillator modes, a five volt regulator for use with a nine volt wall adapter or battery, DB-9 RS-232 interface, ICD connector for programming via ICSP and development with MPLAB ICD 2, 2x16 liquid crystal display, PCB footprints for H-Bridge motor driver, LIN transceiver and EEPROM. Also included are: header for expansion, eight LEDs, four potentiometers, three push buttons and a prototyping area. Included with the kit is a PIC16F627A and a PIC18F1320. Tutorial firmware is included along with the User's Guide.

11.19 PICDEM 17 Demonstration Board

The PICDEM 17 demonstration board is an evaluation board that demonstrates the capabilities of several Microchip microcontrollers, including PIC17C752, PIC17C756A, PIC17C762 and PIC17C766. A programmed sample is included. The PRO MATE II device programmer, or the PICSTART Plus development programmer, can be used to reprogram the device for user tailored application development. The PICDEM 17 demonstration board supports program download and execution from external on-board FLASH memory. A generous prototype area is available for user hardware expansion.

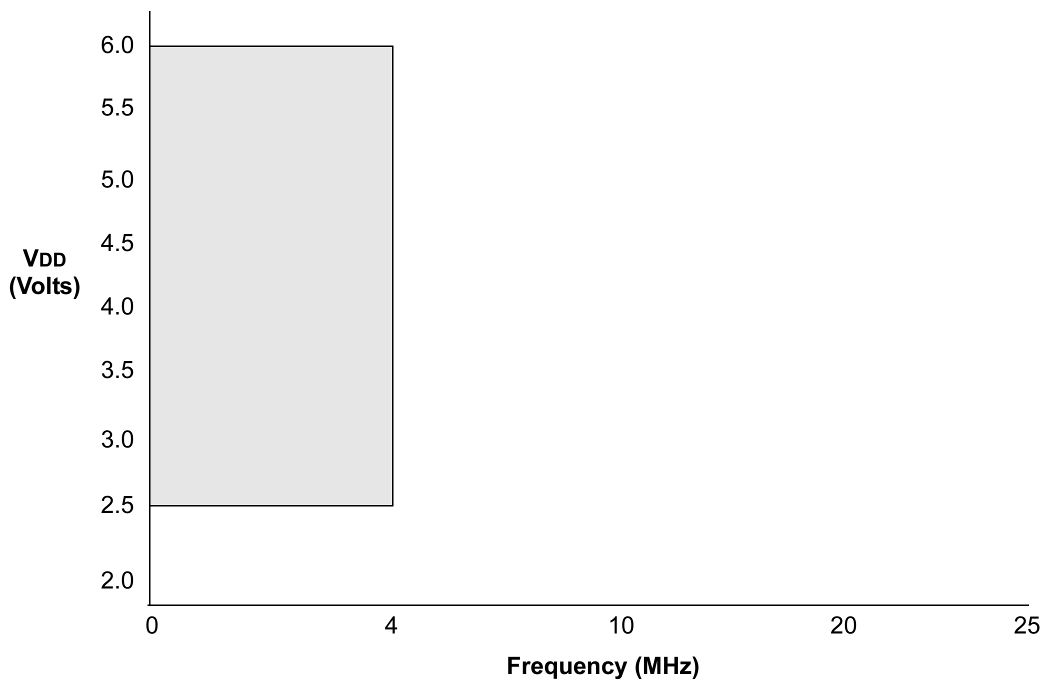
FIGURE 12-1: PIC16C62X VOLTAGE-FREQUENCY GRAPH, -40°C ≤ TA ≤ +125°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

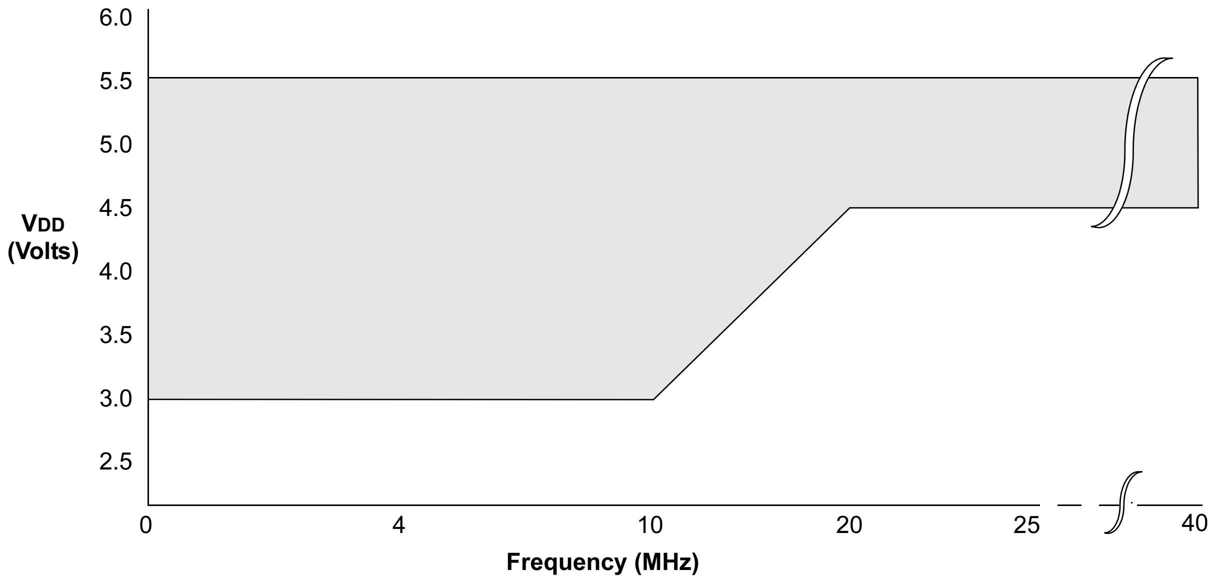
FIGURE 12-2: PIC16LC62X VOLTAGE-FREQUENCY GRAPH, -40°C ≤ TA ≤ +125°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

FIGURE 12-10: PIC16C620A/C621A/C622A/CR620A - 40 VOLTAGE-FREQUENCY GRAPH, 0°C ≤ TA ≤ +70°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

3: Operation between 20 to 40 MHz requires the following:

- VDD between 4.5V. and 5.5V
- OSC1 externally driven
- OSC2 not connected
- HS mode
- Commercial temperatures

Devices qualified for 40 MHz operation have -40 designation (ex: PIC16C620A-40/P).

12.3 DC CHARACTERISTICS: PIC16CR62XA-04 (Commercial, Industrial, Extended) PIC16CR62XA-20 (Commercial, Industrial, Extended) PIC16LCR62XA-04 (Commercial, Industrial, Extended)

PIC16CR62XA-04 **PIC16CR62XA-20**	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended
PIC16LCR62XA-04	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended

Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	3.0	—	5.5	V	See Figures 12-7, 12-8, 12-9
D001	VDD	Supply Voltage	2.5	—	5.5	V	See Figures 12-7, 12-8, 12-9
D002	VDR	RAM Data Retention Voltage(1)	—	1.5*	—	V	Device in SLEEP mode
D002	VDR	RAM Data Retention Voltage(1)	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current(2)	— — — — — —	1.2 500 1.0 4.0 3.0 35	1.7 900 2.0 7.0 6.0 70	mA µA mA mA mA µA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, (**Note 4**)* FOSC = 4 MHz, VDD = 3.0V, WDT disabled, XT mode, (**Note 4**) FOSC = 10 MHz, VDD = 3.0V, WDT disabled, HS mode, (**Note 6**) FOSC = 20 MHz, VDD = 5.5V, WDT disabled*, HS mode FOSC = 20 MHz, VDD = 4.5V, WDT disabled, HS mode FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode
D010	IDD	Supply Current(2)	— — —	1.2 400 35	1.7 800 70	mA µA µA	FOSC = 4.0 MHz, VDD = 5.5V, WDT disabled, XT mode, (**Note 4**)* FOSC = 4.0 MHz, VDD = 2.5V, WDT disabled, XT mode (**Note 4**) FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode

12.4 DC Characteristics: PIC16C62X/C62XA/CR62XA (Commercial, Industrial, Extended) PIC16LC62X/LC62XA/LCR62XA (Commercial, Industrial, Extended) (CONT.)

PIC16C62X/C62XA/CR62XA			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
PIC16LC62X/LC62XA/LCR62XA			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
Param. No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	V_{IH}	Input High Voltage					
		I/O ports					
D040		with TTL buffer	2.0V 0.25 V_{DD} + 0.8V	—	V_{DD} V_{DD}	V	V_{DD} = 4.5V to 5.5V otherwise
D041		with Schmitt Trigger input	0.8 V_{DD}	—	V_{DD}		
D042		$\overline{MCLR}$ RA4/T0CKI	0.8 V_{DD}	—	V_{DD}	V	
D043 D043A		OSC1 (XT, HS and LP) OSC1 (in RC mode)	0.7 V_{DD} 0.9 V_{DD}	—	V_{DD}	V	**(Note 1)**
D070	I_{PURB}	PORTB weak pull-up current	50	200	400	μA	V_{DD} = 5.0V, V_{PIN} = V_{SS}
D070	I_{PURB}	PORTB weak pull-up current	50	200	400	μA	V_{DD} = 5.0V, V_{PIN} = V_{SS}
	I_{IL}	**Input Leakage Current**(2, 3) I/O ports (Except PORTA)			±1.0	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, pin at hi-impedance
D060		PORTA	—	—	±0.5	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, pin at hi-impedance
D061		RA4/T0CKI	—	—	±1.0	μA	$V_{SS} \le V_{PIN} \le V_{DD}$
D063		OSC1, $\overline{MCLR}$	—	—	±5.0	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, XT, HS and LP osc configuration
	I_{IL}	**Input Leakage Current**(2, 3) I/O ports (Except PORTA)			±1.0	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, pin at hi-impedance
D060		PORTA	—	—	±0.5	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, pin at hi-impedance
D061		RA4/T0CKI	—	—	±1.0	μA	$V_{SS} \le V_{PIN} \le V_{DD}$
D063		OSC1, $\overline{MCLR}$	—	—	±5.0	μA	$V_{SS} \le V_{PIN} \le V_{DD}$, XT, HS and LP osc configuration
	V_{OL}	Output Low Voltage					
D080		I/O ports	—	—	0.6	V	I_{OL} = 8.5 mA, V_{DD} = 4.5V, -40° to +85°C
			—	—	0.6	V	I_{OL} = 7.0 mA, V_{DD} = 4.5V, +125°C
D083		OSC2/CLKOUT (RC only)	—	—	0.6	V	I_{OL} = 1.6 mA, V_{DD} = 4.5V, -40° to +85°C
			—	—	0.6	V	I_{OL} = 1.2 mA, V_{DD} = 4.5V, +125°C

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16C62X(A) be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

12.4 DC Characteristics: PIC16C62X/C62XA/CR62XA (Commercial, Industrial, Extended) PIC16LC62X/LC62XA/LCR62XA (Commercial, Industrial, Extended) (CONT.)

PIC16C62X/C62XA/CR62XA			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
PIC16LC62X/LC62XA/LCR62XA			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
Param. No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VOL	Output Low Voltage					
D080		I/O ports	—	—	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40° to +85°C
			—	—	0.6	V	IOL = 7.0 mA, VDD = 4.5V, +125°C
D083		OSC2/CLKOUT (RC only)	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40° to +85°C
			—	—	0.6	V	IOL = 1.2 mA, VDD = 4.5V, +125°C
	VOH	Output High Voltage(3)					
D090		I/O ports (Except RA4)	VDD-0.7	—	—	V	IOH = -3.0 mA, VDD = 4.5V, -40° to +85°C
			VDD-0.7	—	—	V	IOH = -2.5 mA, VDD = 4.5V, +125°C
D092		OSC2/CLKOUT (RC only)	VDD-0.7	—	—	V	IOH = -1.3 mA, VDD = 4.5V, -40° to +85°C
			VDD-0.7	—	—	V	IOH = -1.0 mA, VDD = 4.5V, +125°C
	VOH	Output High Voltage(3)					
D090		I/O ports (Except RA4)	VDD-0.7	—	—	V	IOH = -3.0 mA, VDD = 4.5V, -40° to +85°C
			VDD-0.7	—	—	V	IOH = -2.5 mA, VDD = 4.5V, +125°C
D092		OSC2/CLKOUT (RC only)	VDD-0.7	—	—	V	IOH = -1.3 mA, VDD = 4.5V, -40° to +85°C
			VDD-0.7	—	—	V	IOH = -1.0 mA, VDD = 4.5V, +125°C
*D150	VOD	Open-Drain High Voltage			10* 8.5*	V	RA4 pin PIC16C62X, PIC16LC62X RA4 pin PIC16C62XA, PIC16LC62XA, PIC16CR62XA, PIC16LCR62XA
*D150	VOD	Open-Drain High Voltage			10* 8.5*	V	RA4 pin PIC16C62X, PIC16LC62X RA4 pin PIC16C62XA, PIC16LC62XA, PIC16CR62XA, PIC16LCR62XA
		Capacitive Loading Specs on Output Pins					
D100	COSC2	OSC2 pin			15	pF	In XT, HS and LP modes when external clock used to drive OSC1.
D101	CIO	All I/O pins/OSC2 (in RC mode)			50	pF	
		Capacitive Loading Specs on Output Pins					
D100	COSC2	OSC2 pin			15	pF	In XT, HS and LP modes when external clock used to drive OSC1.
D101	CIO	All I/O pins/OSC2 (in RC mode)			50	pF	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16C62X(A) be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

12.8 Timing Parameter Symbology

The timing parameter symbols have been created with one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

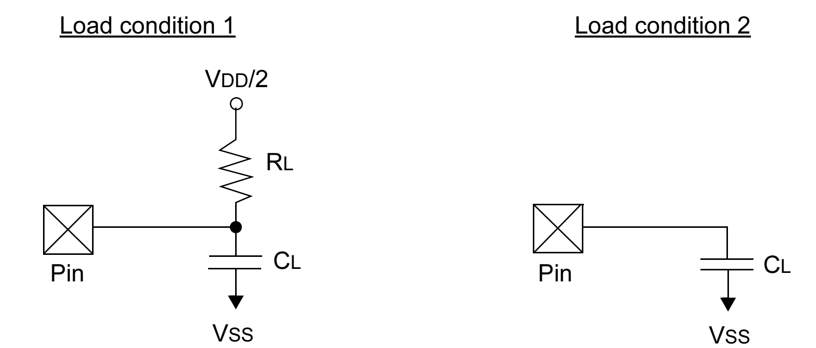
Lowercase subscripts (pp) and their meanings:

pp			
ck	CLKOUT	osc	OSC1
io	I/O port	t0	T0CKI
mc	$\overline{\text{MCLR}}$		

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-Impedance

FIGURE 12-11: LOAD CONDITIONS



R_L = 464Ω

C_L = 50 pF for all pins except OSC2

15 pF for OSC2 output

TABLE 12-4: CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓(1)	— —	75 —	200 400	ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
11*	TosH2ck H	OSC1↑ to CLKOUT↑(1)	— —	75 —	200 400	ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
12*	TckR	CLKOUT rise time(1)	— —	35 —	100 200	ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
13*	TckF	CLKOUT fall time(1)	— —	35 —	100 200	ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
14*	TckL2ioV	CLKOUT ↓ to Port out valid(1)	—	—	20	ns	
15*	TioV2ckH	Port in valid before CLKOUT ↑(1)	TOSC +200 ns TOSC +400 ns	— —	— —	ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
16*	TckH2ioI	Port in hold after CLKOUT ↑(1)	0	—	—	ns	
17*	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid	— —	50	150 300	ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
18*	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	100 200	— —	— —	ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
19*	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	0	—	—	ns	
20*	TioR	Port output rise time	— —	10 —	40 80	ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
21*	TioF	Port output fall time	— —	10 —	40 80	ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
22*	Tinp	RB0/INT pin high or low time	25 40	— —	— —	ns ns	PIC16C62X(A) PIC16LC62X(A) PIC16CR62XA PIC16LCR62XA
23	Trbp	RB<7:4> change interrupt high or low time	TCY	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x TOSC.

FIGURE 12-14: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

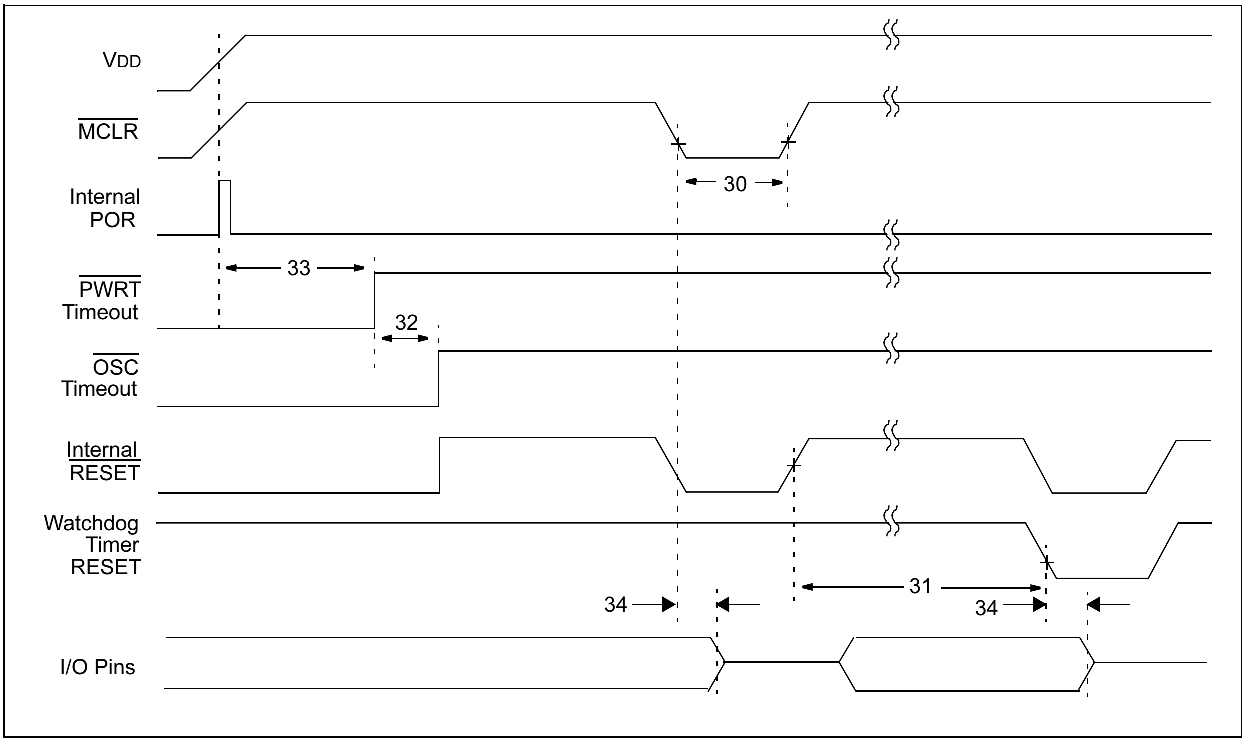


FIGURE 12-15: BROWN-OUT RESET TIMING

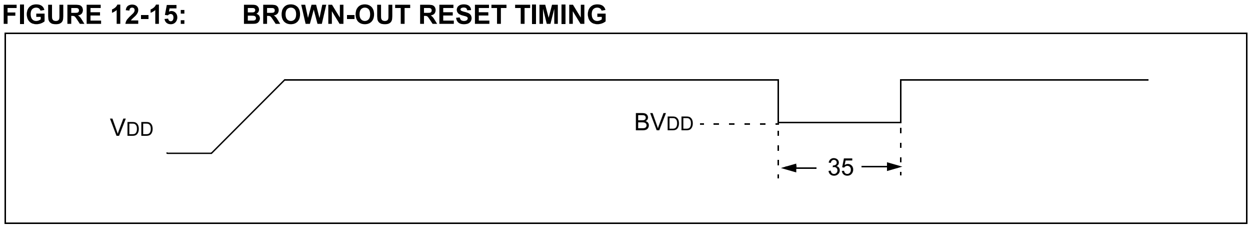


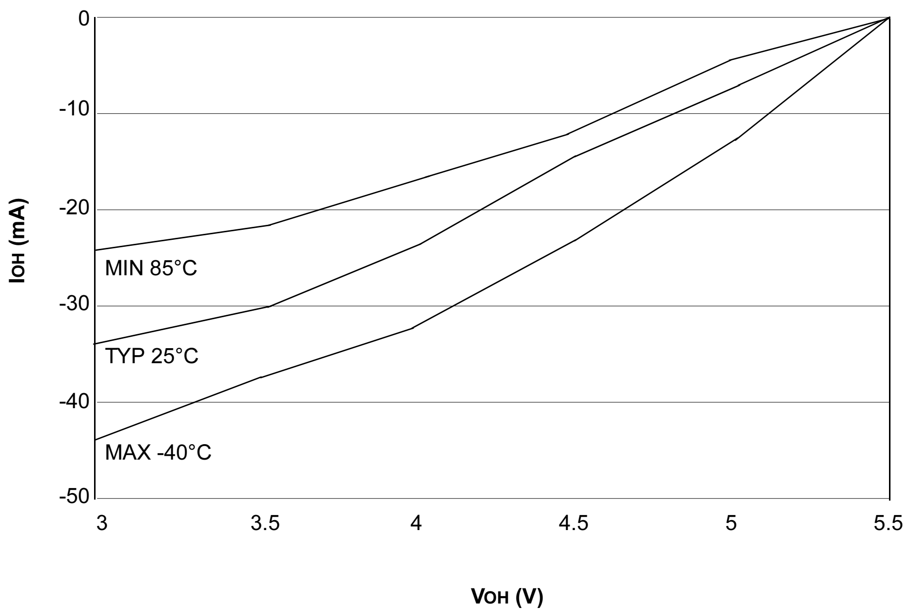
TABLE 12-5: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmcL	$\overline{\text{MCLR}}$ Pulse Width (low)	2000	—	—	ns	-40° to +85°C
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7*	18	33*	ms	VDD = 5.0V, -40° to +85°C
32	Tost	Oscillation Start-up Timer Period	—	1024 TOSC	—	—	TOSC = OSC1 period
33	Tpwrt	Power-up Timer Period	28*	72	132*	ms	VDD = 5.0V, -40° to +85°C
34	TIOZ	I/O hi-impedance from $\overline{\text{MCLR}}$ low		—	2.0	μs	
35	TBOR	Brown-out Reset Pulse Width	100*	—	—	μs	3.7V ≤ VDD ≤ 4.3V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 13-7: I_{OH} VS. V_{OH}, V_{DD} = 5.5V)



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